

ABSTRACT OF THE DISCLOSURE

The present invention provides an electrolytic processing apparatus which is capable of increasing ~~the~~an in-plane uniformity of ~~the~~a film thickness of a plated film by making more uniform an electric field distribution over ~~the~~an entire surface to be processed of a substrate even if the substrate has a large area, and controlling more uniformly ~~the~~a speed, over the entire surface to be processed of the substrate. The electrolytic processing apparatus of this invention ~~including~~includes: a substrate holder for holding a substrate, a first electrode for ~~bringing~~being brought into contact with the substrate to supply current to a surface, to be processed, of the substrate; a second electrode disposed substantially parallel to the surface, to be processed, of the substrate in a position facing the surface, to be processed, of the substrate held by ~~said~~the substrate holder; a high resistance structure disposed between the substrate held by ~~said~~the substrate holder and ~~said~~the second electrode; an electrolytic solution introducing portion for introducing an electrolytic solution into a region across which the substrate held by ~~said~~the substrate holder and ~~said~~the high resistance structure face each other, from laterally of ~~said~~the high resistance structure; and a power source for applying a voltage between ~~said~~the first electrode and ~~said~~the second electrode.